

What is claimed is:

1. A compression bonding method comprising:
patterning a metal bonding film in predetermined shapes on a substrate; and
disposing a bonded element above the metal bonding film and applying heat
5 to the substrate and pressure to the bonded element, thereby bonding the bonded
element to the substrate having the metal bonding film.

2. A compression bonding method comprising:
patterning a first metal bonding film in predetermined shapes on a substrate
10 and patterning a second metal bonding film in the predetermined shapes on a
bonded element; and
disposing the bonded element above the first metal bonding film and applying
heat to the substrate and pressure to the bonded element, thereby bonding the
bonded element having the second metal bonding element to the substrate having
15 the first metal bonding element.

3. The compression bonding method of claim 1 or 2, wherein the
substrate is made of a material selected from the group consisting of silicon, metal,
and ceramic.

4. The compression bonding method of claim 1 or 2, wherein the metal
bonding film is made of a material selected from the group consisting of aluminum,
magnesium, zinc, and titanium.

5. The compression bonding method of claim 1 or 2, wherein the
predetermined shapes are stripes or dots.

6. The compression bonding method of claim 1 or 2, wherein the bonded
element is glass or metal.

7. The compression bonding method of claim 1 or 2, wherein the heat is
lower than 350°C.